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SHENMAO Picks up Award for New Low Temperature Solder at SMTA Guadalajara

SAN JOSE, CA — October 2019 — SHENMAO America, Inc. announces that it was awarded a 2019 Mexico Technology Award in the category of Solder Paste for its PF735-PQ10 Low Temperature Solder (LTS). The award was presented to the company during a Wednesday, Oct. 23, 2019 ceremony that took place during the SMTA Guadalajara Expo & Tech Forum.

PF735-PQ10 is a no clean, zero-halogen, low melting point, lead-free solder paste. The peak reflow temperature of PF735-PQ10 can decrease to as low as 160°C. LTS refers to the solder alloy with liquidus below eutectic Sn/Pb37 (183°C).

Package thickness is reduced as increasing demand for ultra-thin packages. In addition, the reflow temperature of SAC series solder paste is much higher than the glass transition temperature (Tg) of substrates. The warpage becomes a serious issue and generates production yield loss as combining abovementioned factors. LTS paste can reduce the reflow temperature to below 200°C and hence decrease the PCB and substrate deformation.

SHENMAO has successfully been approved by many international well-known electronic manufacturers. The company strives to offer the best quality without compromising cost and time-to-market while providing maximum value to all customers. SHENMAO America, Inc. blends SMT solder paste at its facility in San Jose, CA for distribution in North America.
The Mexico Technology Awards acknowledge the latest innovations available in Mexico produced by OEM manufacturing equipment and materials suppliers over the last 12 months.

For more information, please visit www.shenmao.com.

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About SHENMAO
SHENMAO is dedicated to the production of solder products including Water Soluble and No-clean Solder Paste, Laser Solder Paste, Solder Preforms, Cored Solder Wire, Wave Solder Bar Alloys, Wave Soldering Fluxes, Extremely Pure Solder Powder up to Type 8, BGA and Micro BGA Solder Sphere, Wafer Level Packaging Solder Paste and Fluxes, LED Die Attach Paste, High Performance Liquid Fluxes, Solder Preform, Solar Ribbon, Plating Anode used in PCB Fabrication, Assembly and Semiconductor Packaging Processes.